



INTERNATIONAL ATOMIC ENERGY AGENCY
UNITED NATIONS EDUCATIONAL, SCIENTIFIC AND CULTURAL ORGANIZATION
INTERNATIONAL CENTRE FOR THEORETICAL PHYSICS
I.C.T.P., P.O. BOX 586, 34100 TRIESTE, ITALY, CABLE: CENTRATOM TRIESTE



UNITED NATIONS INDUSTRIAL DEVELOPMENT ORGANIZATION



INTERNATIONAL CENTRE FOR SCIENCE AND HIGH TECHNOLOGY

c/o INTERNATIONAL CENTRE FOR THEORETICAL PHYSICS 34100 TRIESTE (ITALY) VIA GRIGNANO, 9 (ADRIATICO PALACE) P.O. BOX 586 TELEPHONE 040-224572 TELEFAX 040-224575 TELEX 460449 APH I

SMR/542 - 6

**ICTP-INFN
SECOND COURSE ON BASIC VLSI DESIGN TECHNIQUES
18 February - 15 March 1991**

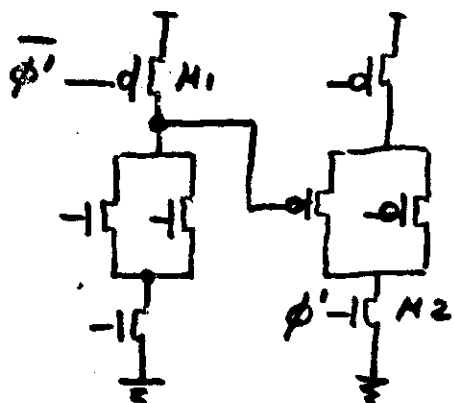
Additional Material to Lectures by

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Western Research Laboratory
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USA**

These are preliminary lecture notes, intended only for distribution to participants.

Zippee Logic

Similar to NORA but with dc 'leaker' property



ϕ' never gets up to V_{DD}
 ϕ' never gets down to GND
 So M_1 & M_2 provides DC current

Good points

It's static (low freq. operation)
 Can recover from charge sharing
 Better than NORA

Bad points

Dc power, uncontrolled
 Still lousy for noise sensitivity

USED IN AT&T 'CRISP' μP but rev. of ACU didn't work

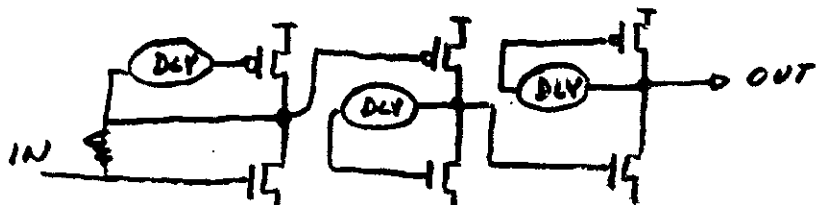
Post-Charge Logic

data is represented by pulses, not levels:

zero :

one :

once a gate has passed an edge, it resets itself T_w later.



No wasted time if logic depth $> T_w$

Example

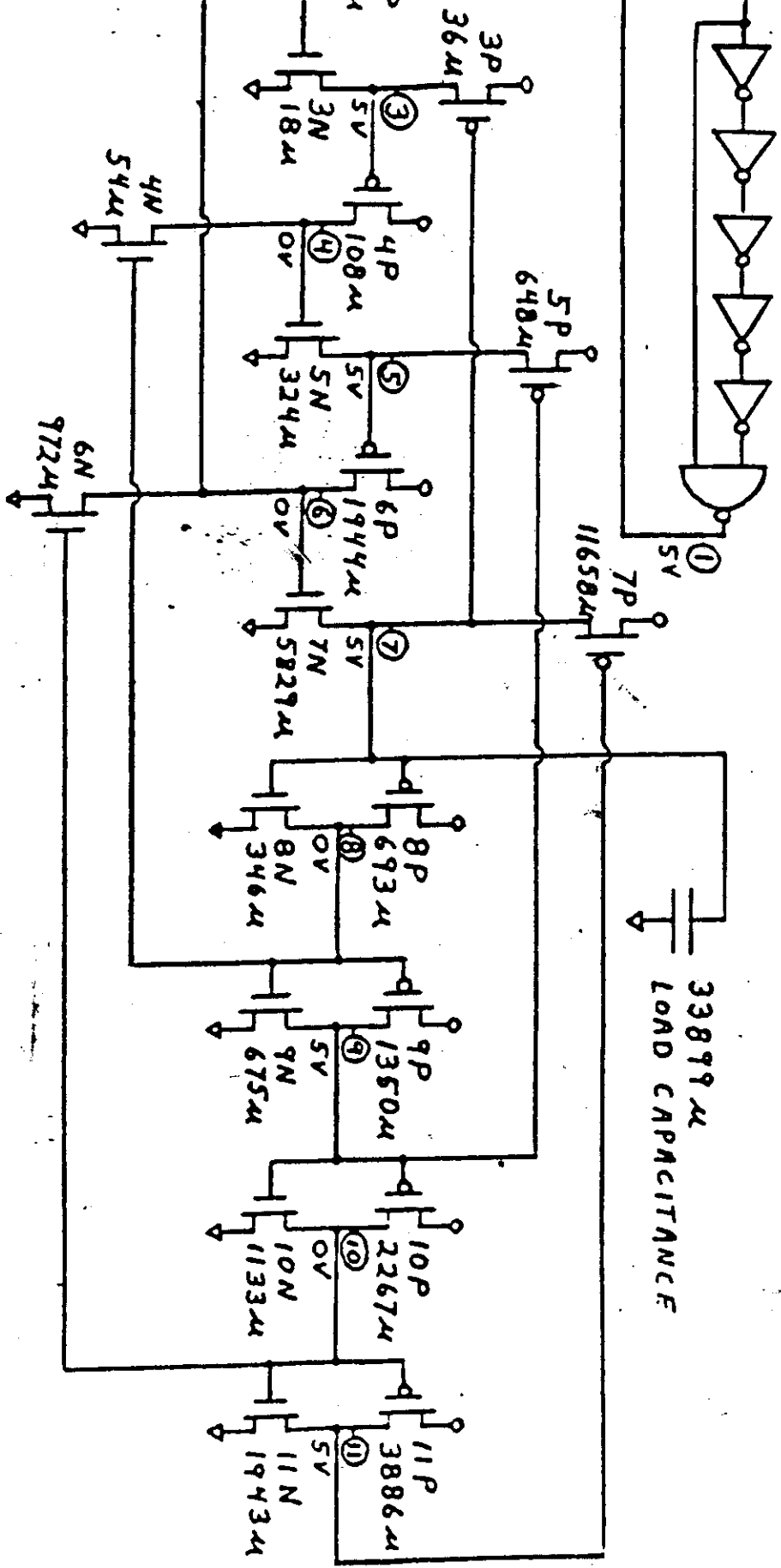
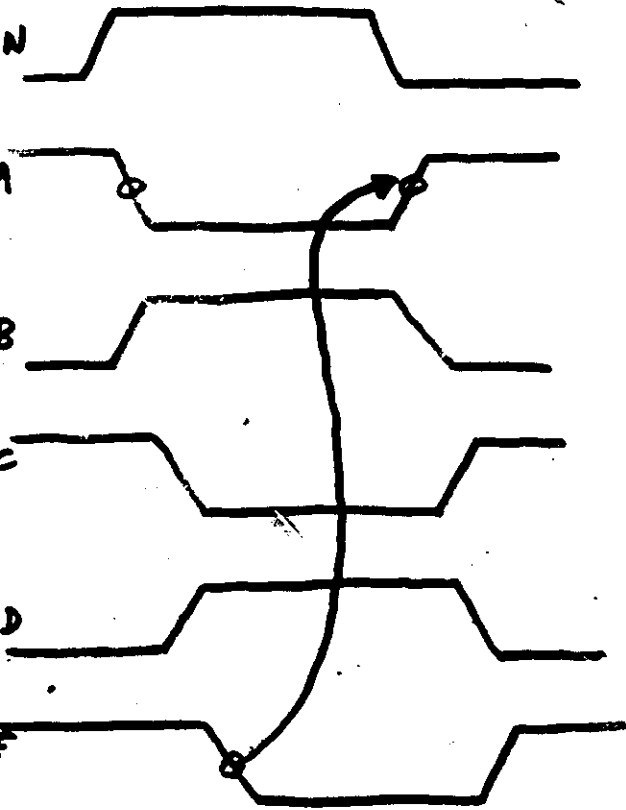


FIG. 2 POST CHARGE LOGIC BUFFER

Post-Charge logic, cont'd



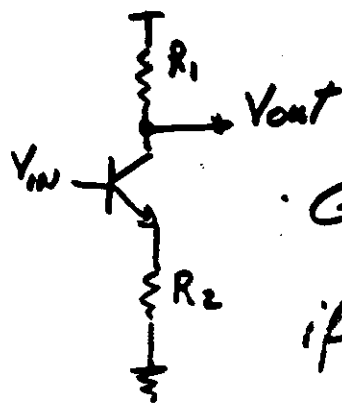
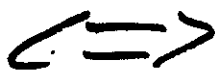
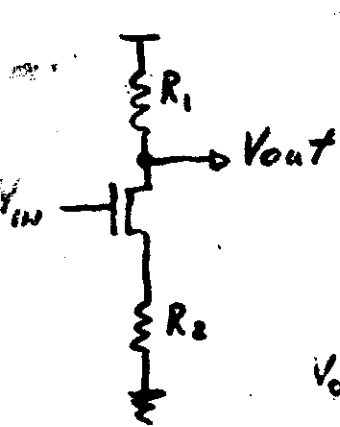
4 stages later causes the post charging

Good Alternating NMOS and PMOS \Rightarrow lower cap \Rightarrow faster

Bad Similar problems to NORA

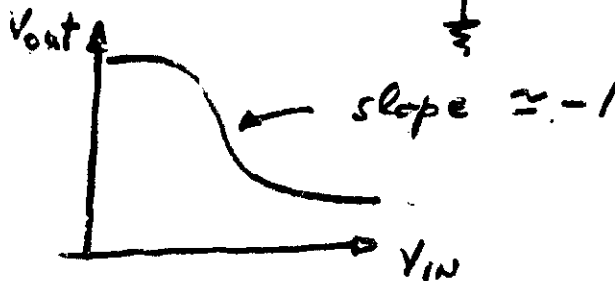
Used in clocked SRAM

NTL (even faster logic family)



$$\text{Gain} = \frac{V_{out}}{V_{in}} \approx -\frac{R_1}{R_2}$$

if $R_1 \approx R_2$ Then gain is ≈ -1

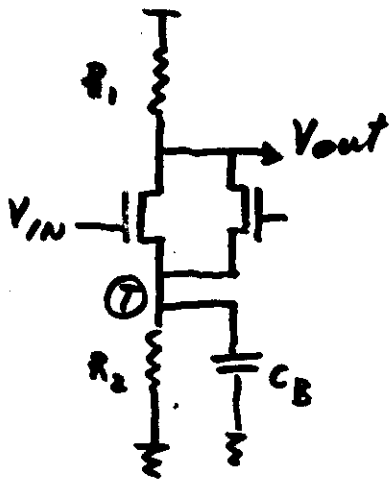


- Output begins moving even before inputs gets halfway point

- "Gain Bandwidth Product" maximizes speed since gain ≈ -1

Unfortunately poor noise rejection compared to static CMOS

NTL cont'd



R_2 supplies negative feedback so, bypass it @ high frequencies

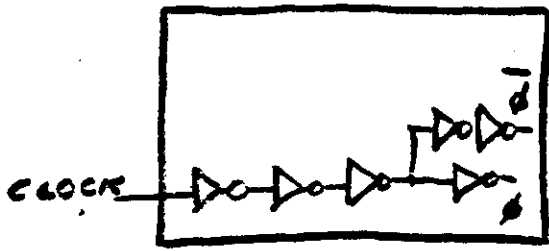
Seems to work great in simulation

BUT

- Consy performance as V_{cc} is varied
- How to get linear resistors in MOS!
- Consy performance as resistors vary (process variations)

$C \ll OCK$ (and fast logic) (add ~~clock~~)

Problem: I/O must be synchronized with external clock

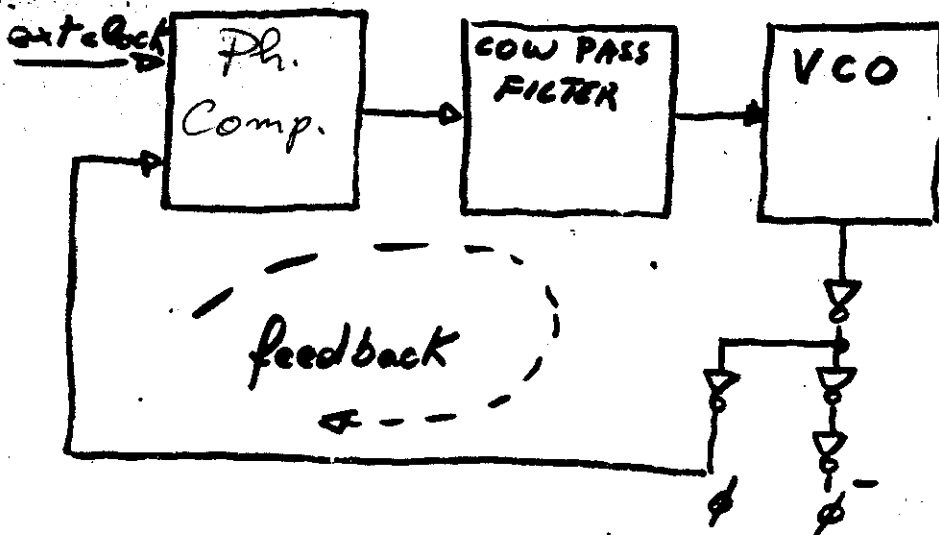


- * On chip clock skewed with respect to off chip clock
- * Sensitive to processing, V_{cc} , temperature ... etc.

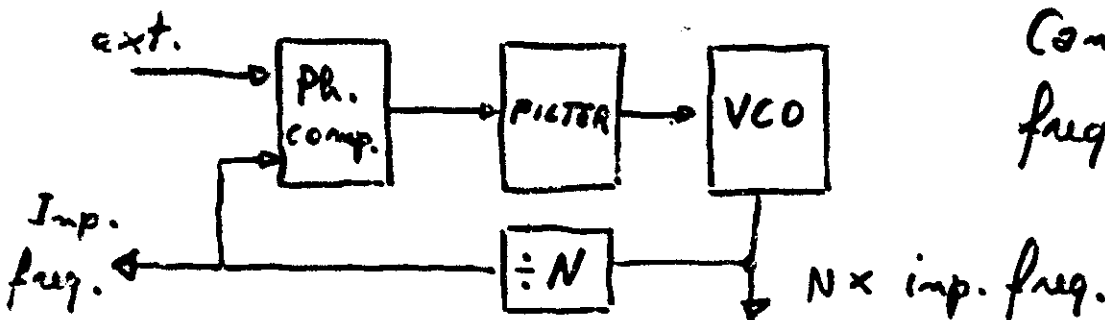
What to do if skew must be very small?

USE PLL (Phase locked loop) to generate ϕ , $\bar{\phi}$ and use feedback to align edges (PHI and CLOCK)

Method 1:



Uses a VCO (Voltage controlled osc.)

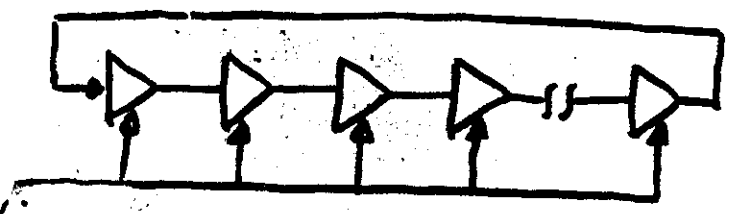
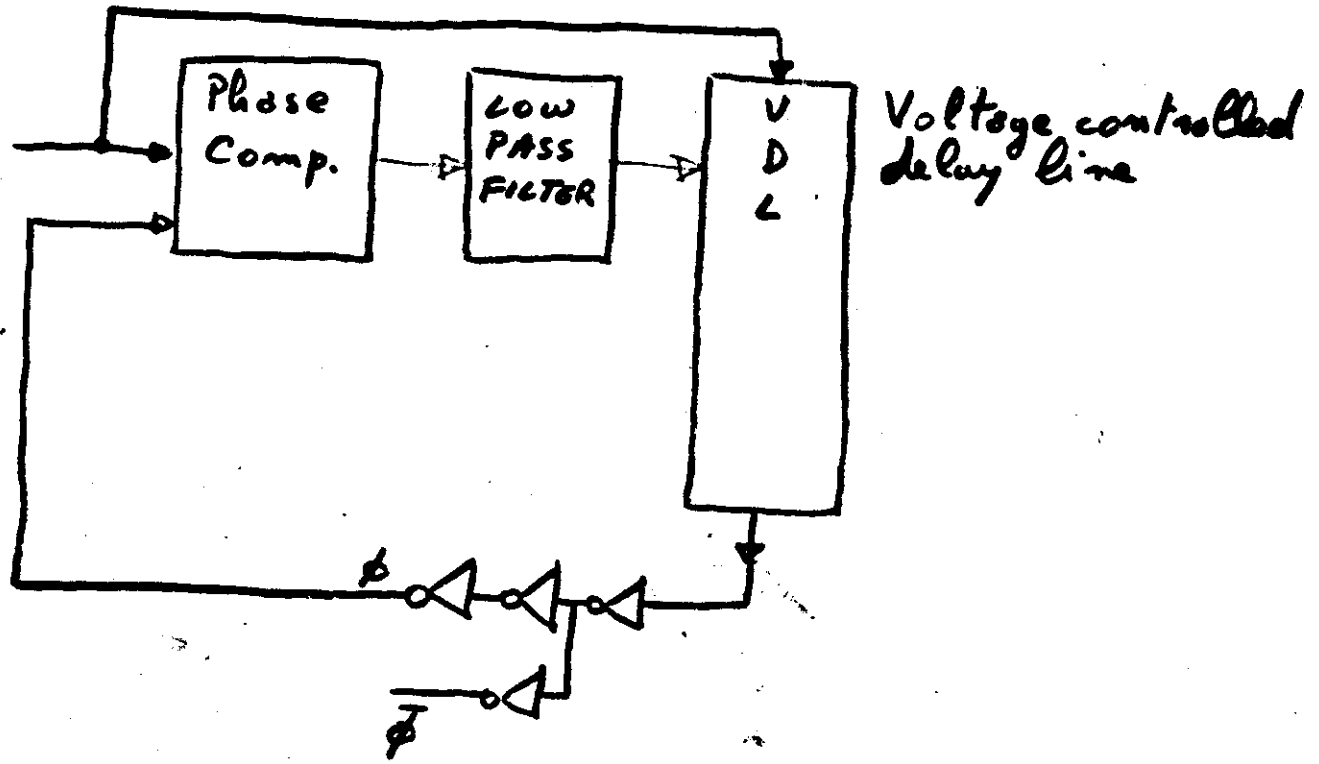


Can multiply input frequency higher

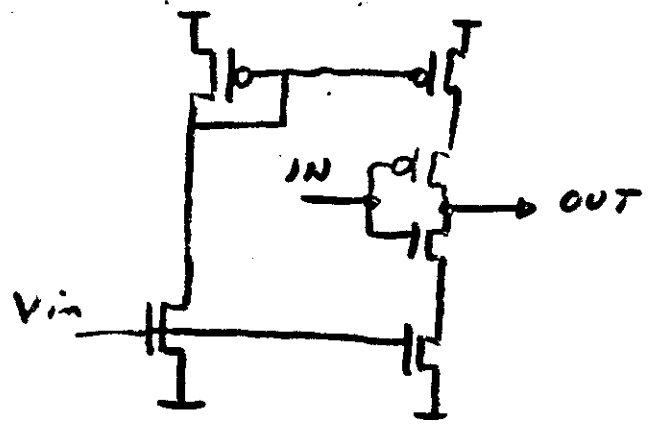
CLOCK

(addendum clock #8)

Method 2



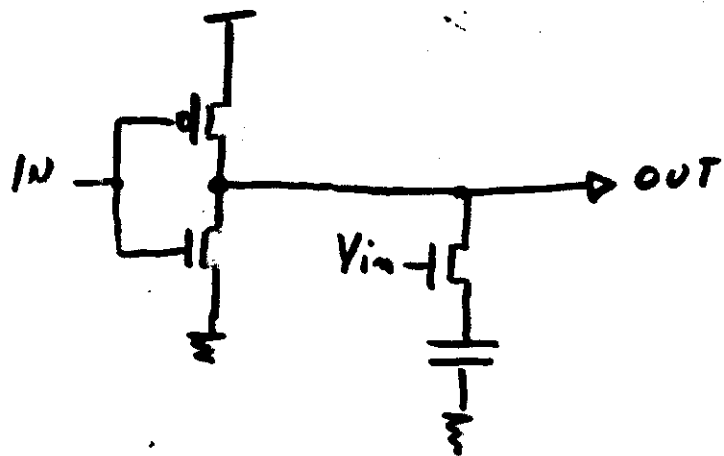
$$f_{\text{req}} = \frac{1}{2 \cdot N \cdot T_{\text{stage}}}$$



Delay $\propto \frac{1}{V_{in}}$ best for VCO application

CCUIC

(addendum 111)
clock



Delay $\propto V_{in}$
 Best for VCDL application

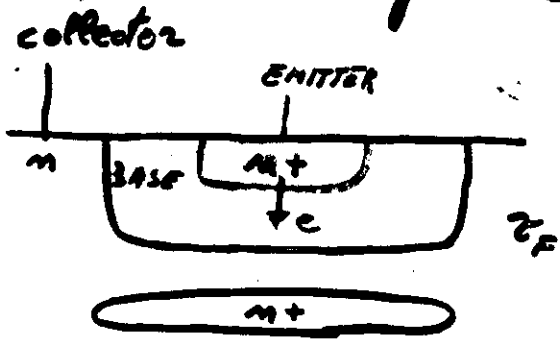
μP with PLL

Inmos	Transputer
Motorola	88000
	68040
MIPS	R3000
Intel	80860, 80486

This is CMOS, in ECL skew must be less than
 100 ps !!!!

Dipolar devices

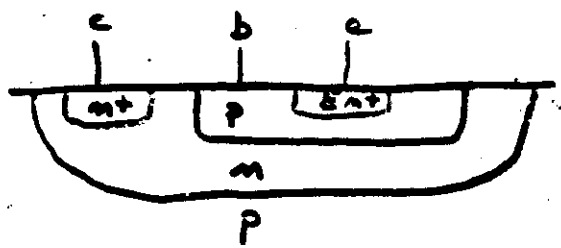
(addendum to #1)



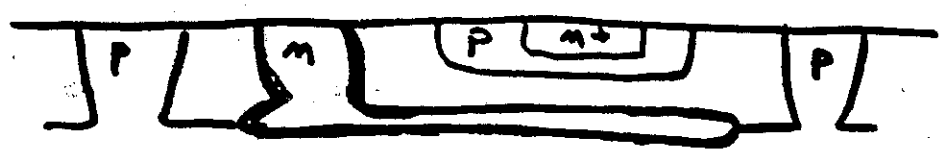
NPN device works by injecting electrons from the emitter to the base. They diffuse across the base and are collected by the collector.

The intrinsic speed is set by the base width, dimension controlled by 2 implants. ($\sim 0.1\mu$)

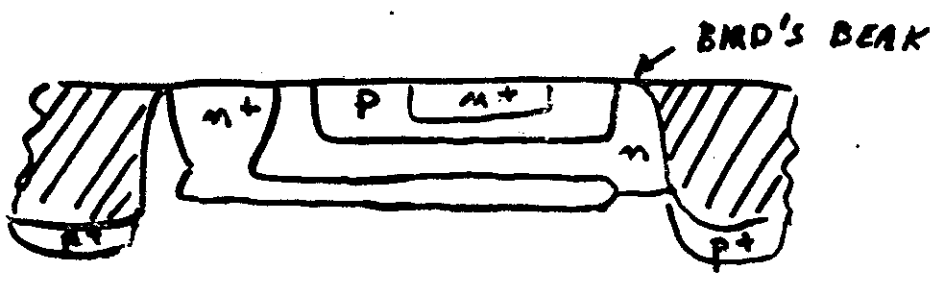
TRIPLE DIFFUSED



JUNCTION ISOLATED with buried layer

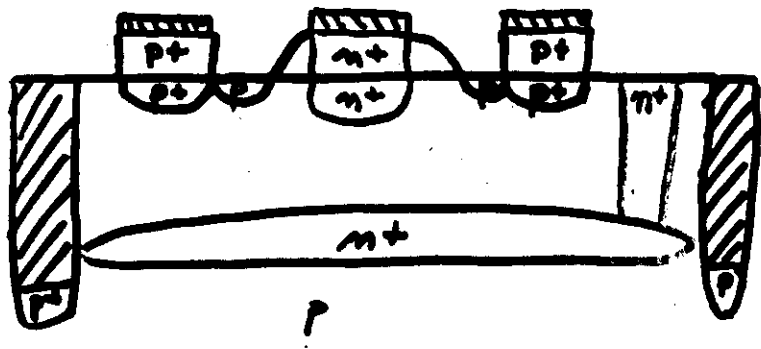


WIDE-ISOLATED (LOCOS STYLE)

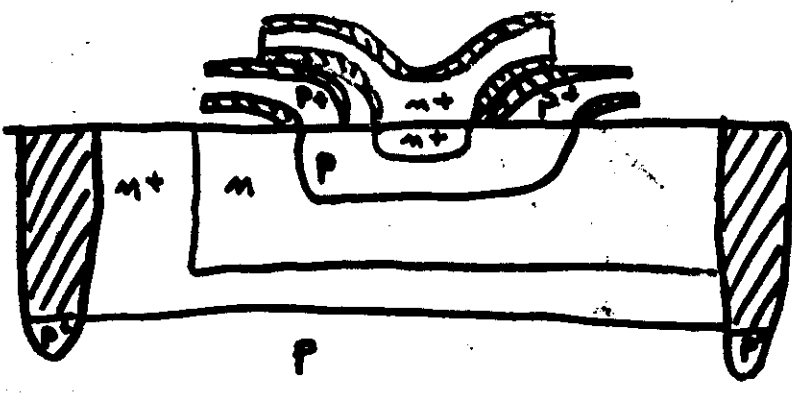


- Poly emitters
- Trenches

SINGLE POLY



DOUBLE POLY



Basic operation

Base-emitter forward biased

Base-collector reverse biased

$$I_c = \frac{q D_n n_i^2 A_e}{N_A W_b} e^{\frac{q V_{be}}{kT}}$$

for circuits :

$$I_c = I_s e^{\frac{V_{be}}{V_T}}$$

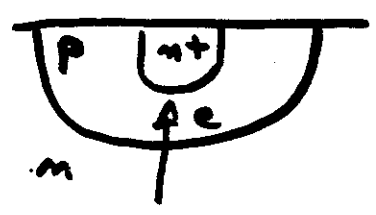
$$V_T = \frac{kT}{q}$$

$$\beta = \frac{I_c}{I_B}$$

V_T	Temp °C
23.5	0
25.9	27
30.6	85
34.3	125

Dipolar carrier (area of n^+)

SATURATION \Rightarrow C.B junctions are forward biased
The upward acting i_{ns}



It works the same way as the down i_{ns} , but smaller β because of area mismatch (can be 5-10)

When saturation starts?

When there is an appreciable current

$$\frac{i_{up}}{i_{down}} \approx e^{-V_{ce}/V_T}$$

So V_{be} can be positive (400 mV or less) without serious problems ("soft saturation")

Additional charge stores in the base of the device
It should be avoided !!

NORMAL

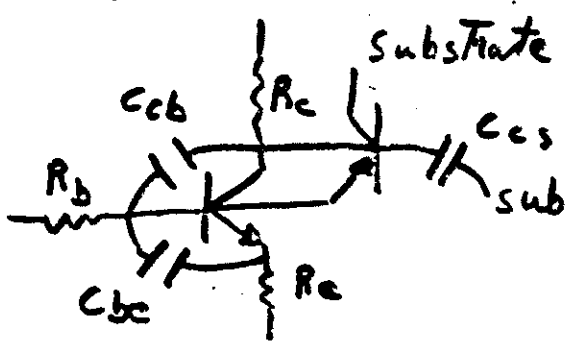
$$Q = i_c \cdot \tau_F$$

SATURATION

$$Q = i_{up} \tau_{up} + i_{down} \tau_{down}$$

$$i = i_{down} - i_{up}$$

$$\tau_{up} \gg \tau_{down}$$



TODAY'S TYPICAL VALUES

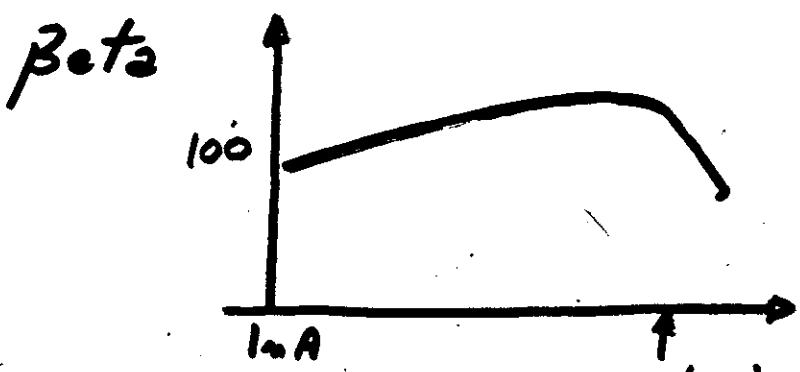
- C_{cb} 6-8 fF
- C_{bc} 8-12 fF
- C_{cs} 25-30 fF

Dipole eq.

(as a. imp)

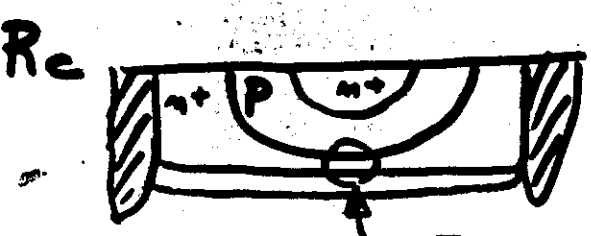
$$f_T = \frac{1}{2\pi \left(1 + \frac{C_{je} + C_{ic}}{g_m \tau_F}\right) \tau_F} \approx \frac{1}{2\pi \tau_F} \quad \tau_F \approx 10-15 \text{ ps}$$

$$\approx 10-15 \text{ GHz typical}$$

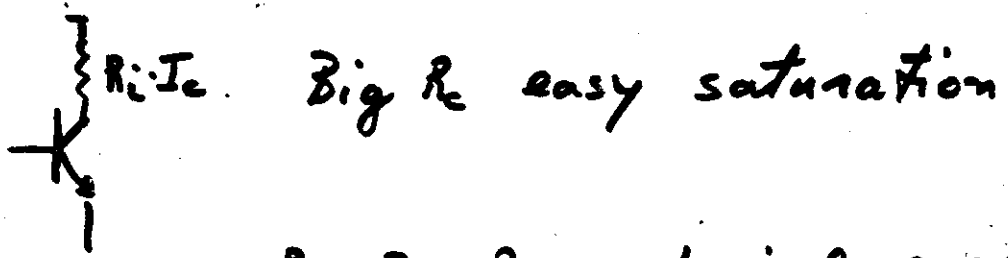


typical $200 \mu\text{A}/\mu\text{m}$ current density

instead of e^{V/V_T} $e^{V/2V_T}$ "high level injection"

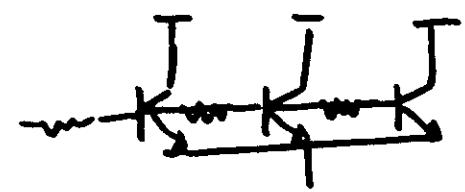
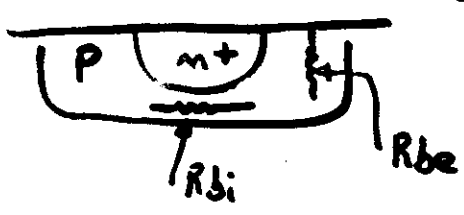


vertical part under emitter $R_c \approx 80-100 \Omega$



Big R_c easy saturation

$$R_b = R_{bi} + R_{be} \quad \text{typical} \approx 200-500 \Omega/\square$$



At higher current voltage drop

It will certainly be the tech. of the 90's, but only if there will be a different implementation in the Gate Arrays. (If 2 bipolar trs are used in each cell, then too much wasted area)

2 ways to apply BiCMOS

1) Large-Swing (CMOS like)

2) Small-Swing (ECL like)

Large number of possible GOOD circuits !!

Good properties of bipolar

1) High i/area

2) High i/cap

3) good matching

4) high gain/ g_m

Watch out for:

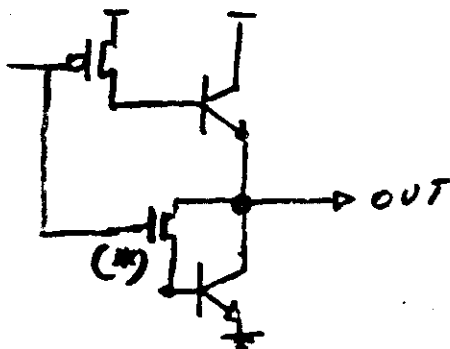
1) Saturation

2) Voltage drop

3) Noise

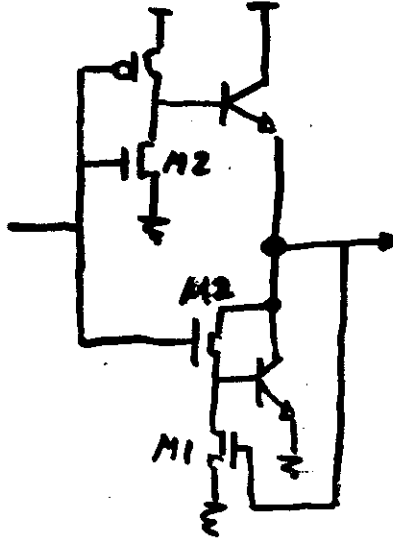
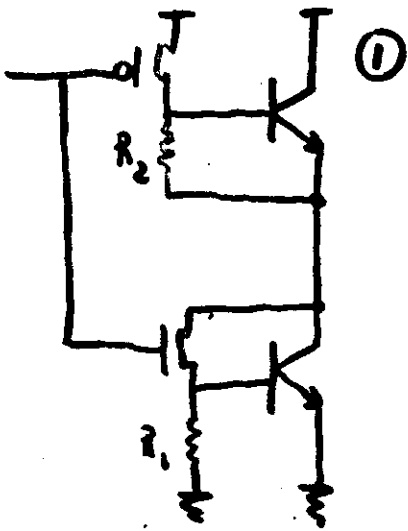
4) High current effects

The classical circuit



(*) Keeps the bipolar out of saturation

Other options: (to turn off bipolar when not active)



& R_2 large so they
 don't steal too much
 current but need to keep
 device off

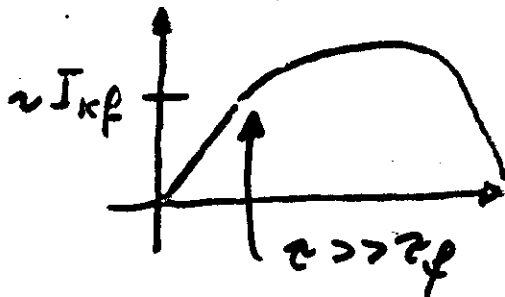
M_1 small compared to M_3
 M_2 small

What size bipolars?

Larger \Rightarrow more area
 more cap.
 more current

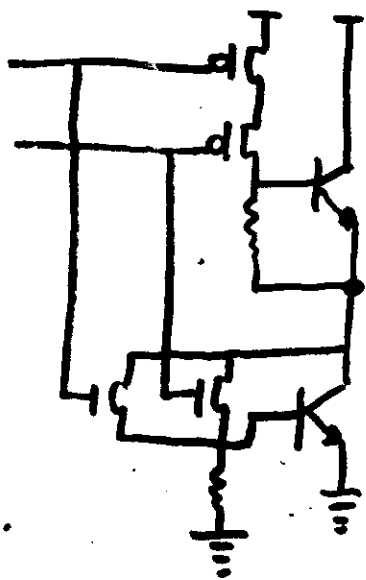


$I \propto e^{V/V_T}$ but.....
 after a point τ_{cs} falls apart



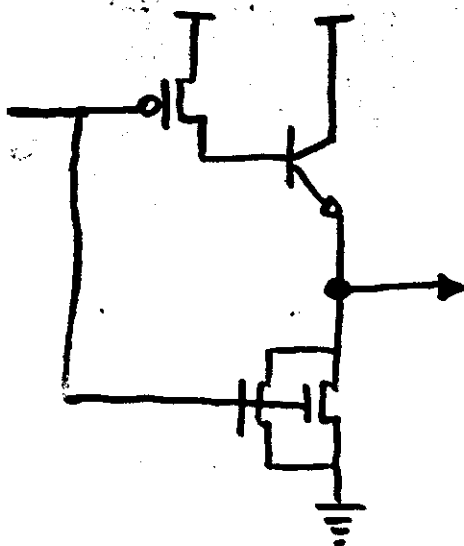
BiCMOS (addendum #3) ^(104c)

A BiCMOS buffer can do logic too:



NOR Implementation

Why should we use 2 bipolars in each cell?

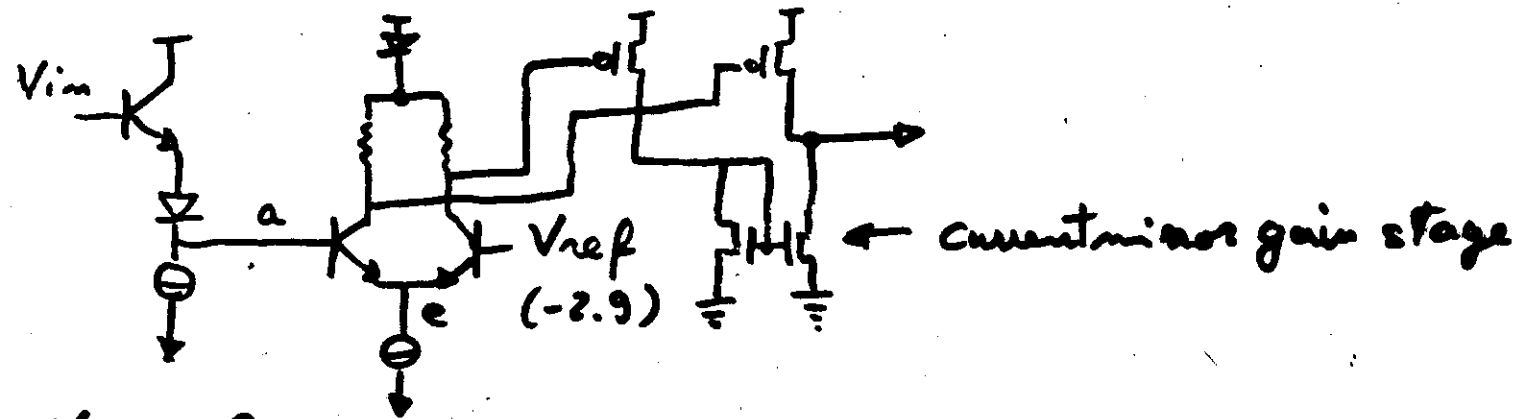


Only \uparrow improved by the bipolar. \downarrow is good enough in many cases.

In a gate array implementation, this saves a lot of space. But if we have a very large capacitance?

Level conversion

Basic Idea (Hitachi)



$$V_{in} = .9$$

$$V_a = -2.5$$

$$V_e = -3.7$$

From Addison-Wesley
VLSI Systems Series
listing:

- Analog VLSI and Neural Systems
by Mead, 1989
- Computer Aids for VLSI Design
by Rubin, 1984
- Principles of CMOS VLSI Design:
A Systems Perspective by Weste
and Eshraghian, 1985
- The Design and Analysis of
VLSI Circuits, by Glasser and
Dobberpuhl, 1985.
- Introduction to VLSI Systems
by Mead and Conway, 1980.

